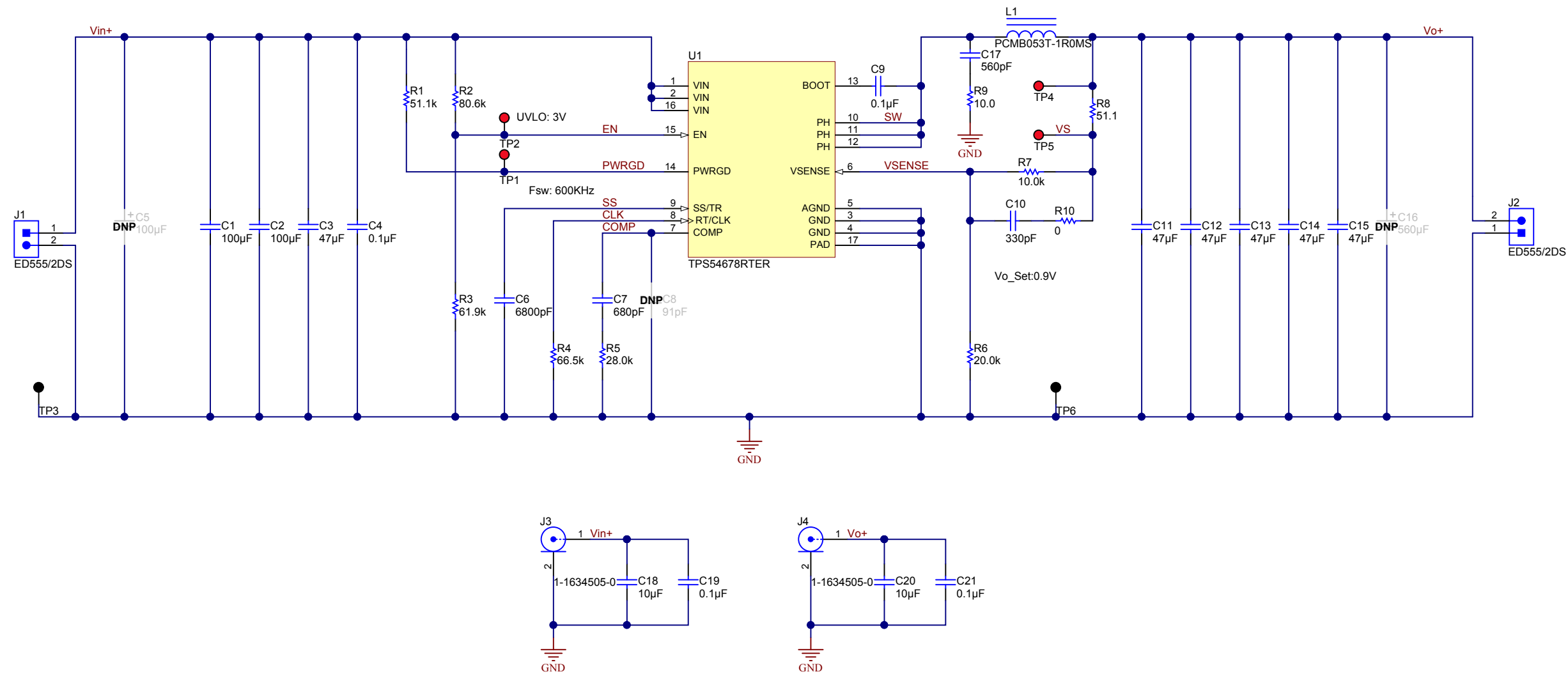


Revision History	
Revision	Notes
1.0	The first version for review
1.1	Add snubber; Optimize divider
1.2	Add two BNC ports
1.3	Add two MLCCs for BNCs
1.4	Update parameters based on test results



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TID #: PMP4481	Project Title: 3-6Vin, 0.6-3.3Vo/6A pico module reference design		
Number: PMP4481	Rev: 1.4	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2	
Drawn By:	File: PMP4481_Main Circuit.SchDoc	Size: B	
Engineer: Yingyang Ou	Contact: http://www.ti.com/support		

H3 DNP NY PMS 440 0025 PH
 H6 DNP NY PMS 440 0025 PH
 H9 DNP NY PMS 440 0025 PH
 H12 DNP NY PMS 440 0025 PH

H2 DNP 1902C
 H5 DNP 1902C
 H8 DNP 1902C
 H11 DNP 1902C

DNP FID1
 DNP FID2
 DNP FID3

PCB Number: PMP4481
 PCB Rev: 1.0

PCB
 LOGO
 Pb-Free Symbol

Label Table	
Variant	Label Text
001	No Al-cap

ZZ1
Assembly Note
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Drawn By:	File: PMP4481 Hardware.SchDoc	Size: B
Engineer: Yingyang Ou	Contact: http://www.ti.com/support	



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